

RELIABILITY DATA

LT1187 / 1189 / 1190 / 1191 / 1192 / 1193 / 1194 / 1195

6/17/04

• OPERATING LIFE TEST

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS ⁽¹⁾ AT +125°C	NUMBER OF ⁽²⁾ FAILURES
CERDIP	558	9130	0129	561.47	0
PLASTIC DIP	6,418	9130	0320	7,491.83	0
SOIC/SOT/MSOP	578	9308	9850	864.73	0
	7,554			8,918.03	0

• HIGHLY ACCELERATED STRESS TEST AT +131°C/85%RH

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS AT +85°C ⁽⁴⁾	NUMBER OF FAILURES
PLASTIC DIP	292	9443	9703	519.56	0
SOIC/SOT/MSOP	299	9902	0101	287.04	0
	591			806.60	0

• PRESSURE COOKER TEST AT 15 PSIG, +121°C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS	NUMBER OF FAILURES
PLASTIC DIP	7,673	9225	0041	457.13	0
SOIC/SOT/MSOP	4,572	9217	0122	460.15	0
	12,245			917.29	0

• TEMP CYCLE FROM -65°C to +150°C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
CERDIP	17	0129	0129	1.70	0
PLASTIC DIP	542	9302	9810	238.91	0
SOIC/SOT/MSOP	1,035	9250	0122	493.46	0
	1,594			734.07	0

• THERMAL SHOCK FROM -65°C to +150°C

PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
CERDIP	17	0129	0129	0.26	0
PLASTIC DIP	304	9443	9810	103.40	0
SOIC/SOT/MSOP	775	9217	0004	224.06	0
	1,096			327.71	0

(1) Assumes Activation Energy = 1.0 Electron Volts
 (2) Failure Rate Equivalent to +55°C, 60% Confidence Level = 0.21 FITS
 (3) Mean Time Between Failures in Years = 543,224
 (4) Assumes 20X Acceleration from 85°C to +131°C
 Note: 1 FIT = 1 Failure in One Billion Hours.